

BGF128

HDMI Interface ESD Protection

RF & Protection Devices



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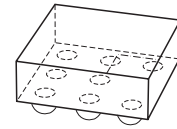
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BGF128

Features

- ESD protection circuit for control data lines of an HDMI interface
- ESD protection according to IEC61000-4-2 for ± 15 kV contact discharge on external IOs
- Wafer level package with SnAgCu solder balls
- 400 μm solder ball pitch
- RoHS and WEEE compliant package



WLP-8-9-N-3D



Description

BGF128 is an ESD protection circuit for control data lines of an HDMI interface. All external IOs are protected against ESD pulses of ± 15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green lead-free and halogen-free package with a size of only 1.15 mm x 1.15 mm and a total height of 0.6 mm.

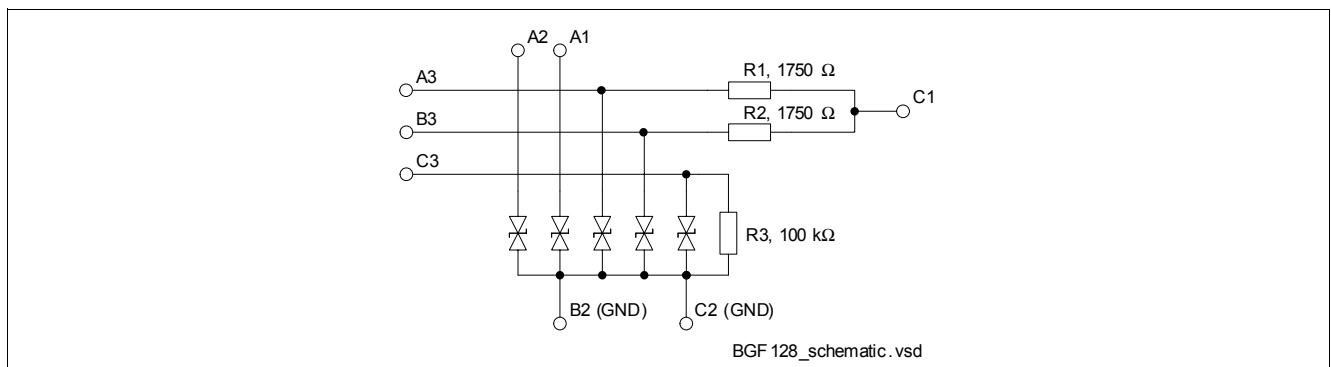


Figure 1 Schematic

Type	Package	Marking	Chip
BGF128	WLP-8-9	28	N0747

Table 1 Maximum Ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Voltage at all pins to GND	V_P	0	–	5	V	–
Operating temperature range	T_{OP}	-40	–	+85	$^{\circ}\text{C}$	–
Storage temperature range	T_{STG}	-65	–	+150	$^{\circ}\text{C}$	–
Summed up input power for all pins	P_{in}	–	–	60	mW	$T_S < 70^{\circ}\text{C}$

Electrostatic Discharge According to IEC61000-4-2

Contact discharge at internal pin C1 to any other pin	V_{ESD}	-2	–	2	kV	–
Contact discharge at external pins A1, A2, A3, B3, C3 to GND	V_{ESD}	-15	–	15	kV	–

Table 2 Electrical Characteristics¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Resistors R_1, R_2	$R_{1,2}$	1575	1750	1925	Ω	–
Resistor R_3	R_3	80	100	120	$k\Omega$	–
Leakage current of ESD protection diodes	I_R	–	1	100	nA	$V = 3\text{ V}$
		–	2	200	nA	$V = 5\text{ V}$
Breakdown voltage of ESD diodes ²⁾	$V_{(BR)}$	–	18.5 -12.5	–	V	$I_{(BR)} = 1\text{ mA}$ $I_{(BR)} = -1\text{ mA}$
Line capacitance A1, A2, A3, B3, C3 ³⁾	C_T	8	10	12	pF	$V = 0\text{ V}$

1) at $T_A = 25\text{ }^\circ\text{C}$

2) after snap-back

3) Capacitance measured from designated pin to GND. Pin C1 connected to GND.

Package Outlines

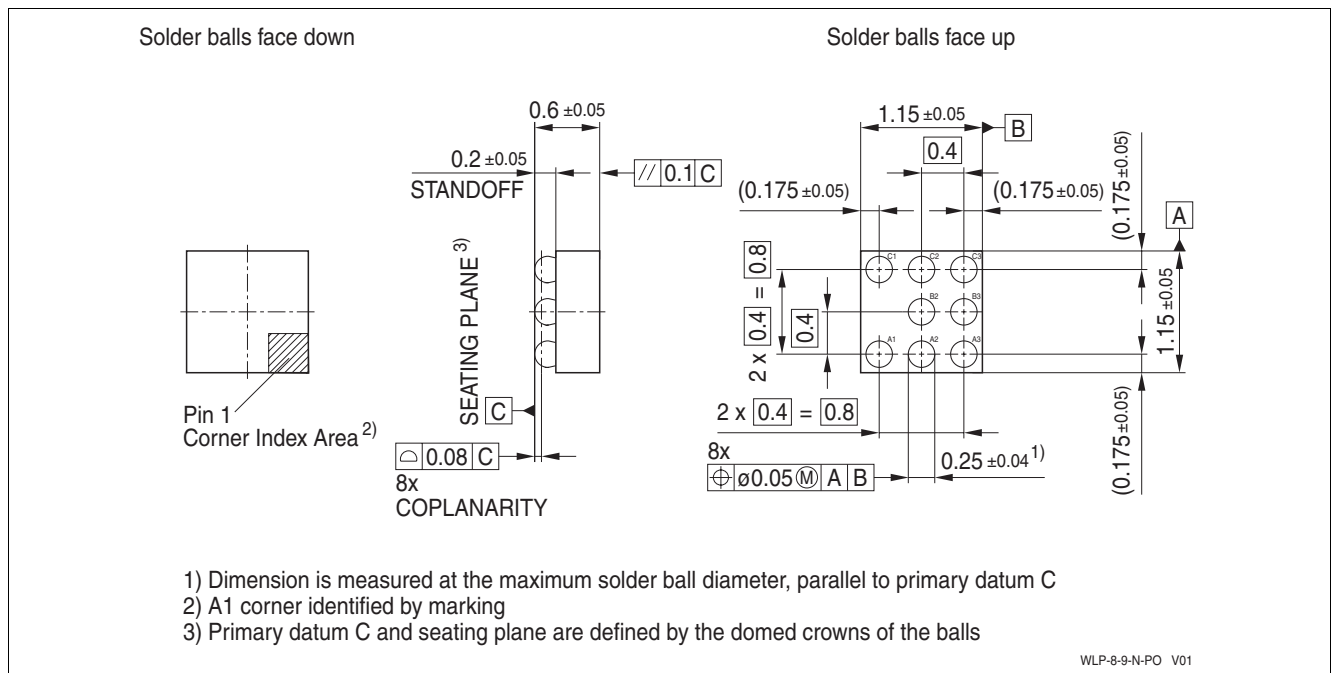


Figure 2 Package WLP-8-9

Footprint

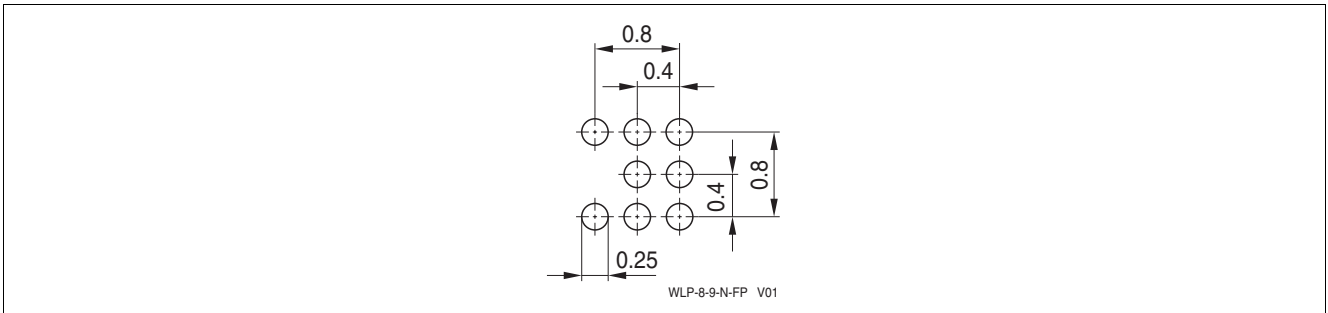


Figure 3 Recommended PCB pad design for reflow soldering

Tape

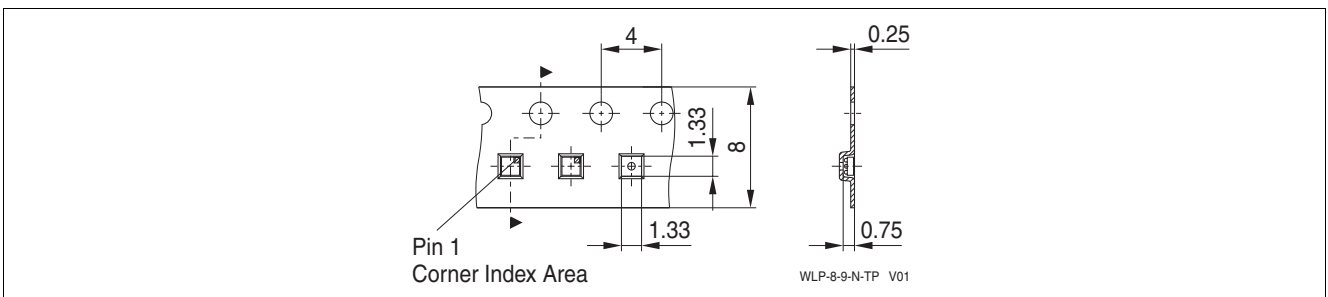


Figure 4 Tape for WLP-8-9

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